



Material Content Data Sheet



Sales Product Name		TLE82452SA		Issued		28. August 2013		
MA#		MA001139902						
Package		PG-DSO-36-54		Weight*		2107.84 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	22.403	1.06	1.06	10628	10628
leadframe	inorganic material	phosphorus	7723-14-0	0.388	0.02		184	
	non noble metal	zinc	7440-66-6	1.553	0.07		737	
	non noble metal	iron	7439-89-6	31.066	1.47		14738	
wire	non noble metal	copper	7440-50-8	1261.410	59.86	61.42	598439	614098
	non noble metal	copper	7440-50-8	2.515	0.12	0.12	1193	1193
	encapsulation	organic material	carbon black	1333-86-4	1.516	0.07		719
encapsulation	plastics	epoxy resin	-	69.718	3.31		33076	
	inorganic material	silicondioxide	60676-86-0	686.573	32.57	35.95	325724	359519
leadfinish	non noble metal	tin	7440-31-5	15.044	0.71	0.71	7137	7137
plating	noble metal	silver	7440-22-4	0.644	0.03	0.03	305	305
solder	noble metal	silver	7440-22-4	0.225	0.01		107	
	non noble metal	tin	7440-31-5	0.150	0.01		71	
	non noble metal	lead	7439-92-1	14.633	0.69	0.71	6942	7120
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

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